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## Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

### Details

Product Status	Obsolete
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	101
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	132-LFBGA, CSPBGA
Supplier Device Package	132-CSPBGA (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200e-4m132i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200e-4m132i</a>

## Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single chip, no external configuration memory required
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through JTAG port
  - Supports background programming of non-volatile memory
- **Sleep Mode**
  - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **High I/O to Logic Density**
  - 256 to 2280 LUT4s
  - 73 to 271 I/Os with extensive package options
  - Density migration supported
  - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
  - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
  - Up to 7.7 Kbits distributed RAM
  - Dedicated FIFO control logic

- **Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTTL
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **sysCLOCK™ PLLs**
  - Up to two analog PLLs per device
  - Clock multiply, divide, and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan
  - Onboard oscillator
  - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
  - IEEE 1532 compliant in-system programming

## Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

**Table 1-1. MachXO Family Selection Guide**

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V <sub>CC</sub> Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
<b>Packages</b>				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

## Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

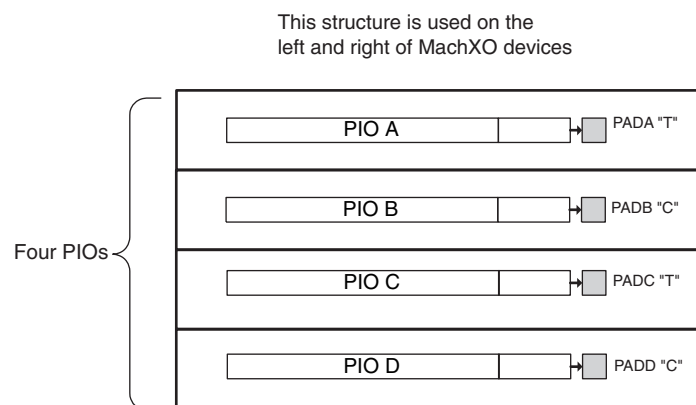
## PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

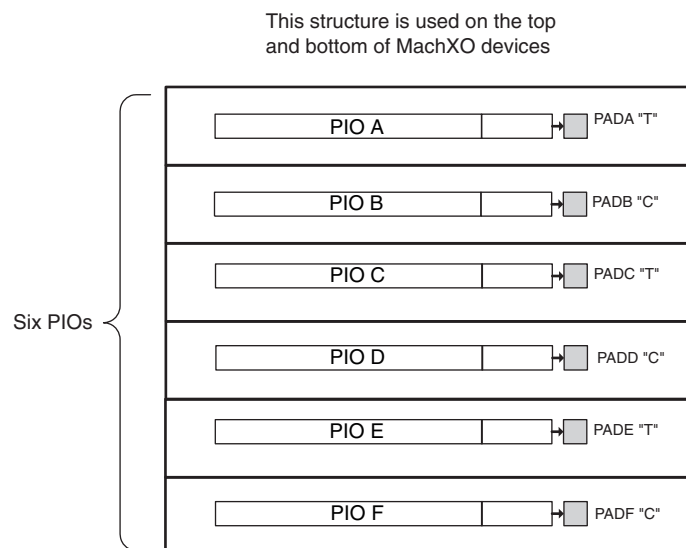
On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

**Figure 2-15. Group of Four Programmable I/O Cells**



**Figure 2-16. Group of Six Programmable I/O Cells**



## PIO

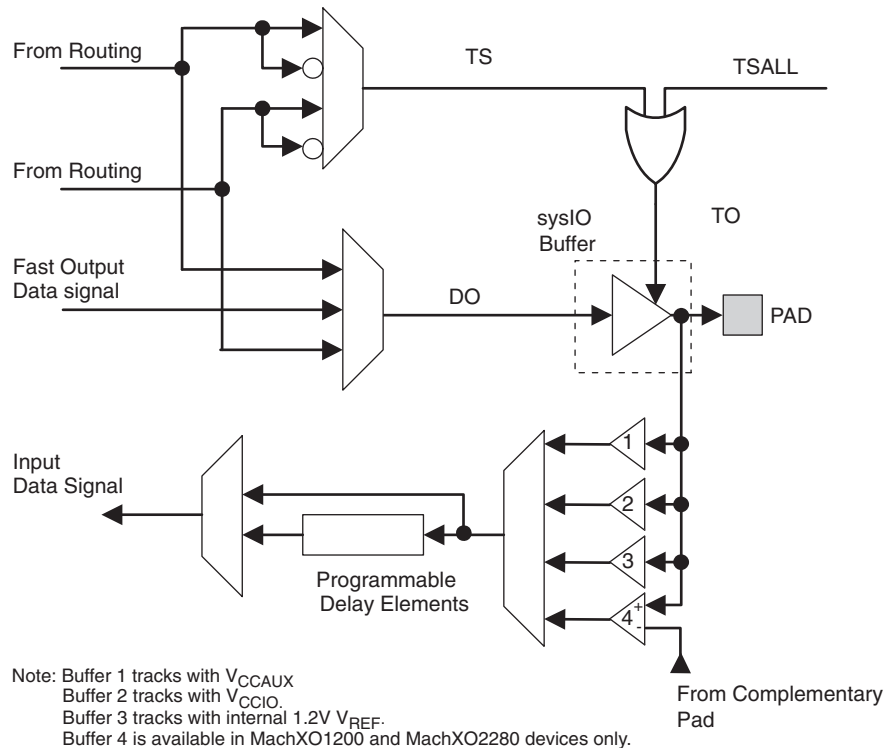
The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

output data signals are multiplexed and provide a single signal to the I/O pin via the sysIO buffer. Figure 2-17 shows the MachXO PIO logic.

The tristate control signal is multiplexed from the output data signals and their complements. In addition a global signal (TSALL) from a dedicated pad can be used to tristate the sysIO buffer.

The PIO receives an input signal from the pin via the sysIO buffer and provides this signal to the core of the device. In addition there are programmable elements that can be utilized by the design tools to avoid positive hold times.

**Figure 2-17. MachXO PIO Block Diagram**



## sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, TTL, BLVDS, LVDS and LVPECL.

In the MachXO devices, single-ended output buffers and ratioed input buffers (LVTTTL, LVCMOS and PCI) are powered using  $V_{CCIO}$ . In addition to the Bank  $V_{CCIO}$  supplies, the MachXO devices have a  $V_{CC}$  core logic power supply, and a  $V_{CCAUX}$  supply that powers up a variety of internal circuits including all the differential and referenced input buffers.

MachXO256 and MachXO640 devices contain single-ended input buffers and single-ended output buffers with complementary outputs on all the I/O Banks.

MachXO1200 and MachXO2280 devices contain two types of sysIO buffer pairs.

### 1. Top and Bottom sysIO Buffer Pairs

The sysIO buffer pairs in the top and bottom Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (for ratioed or absolute input levels). The I/O pairs on the top and bottom

Figure 2-18. MachXO2280 Banks

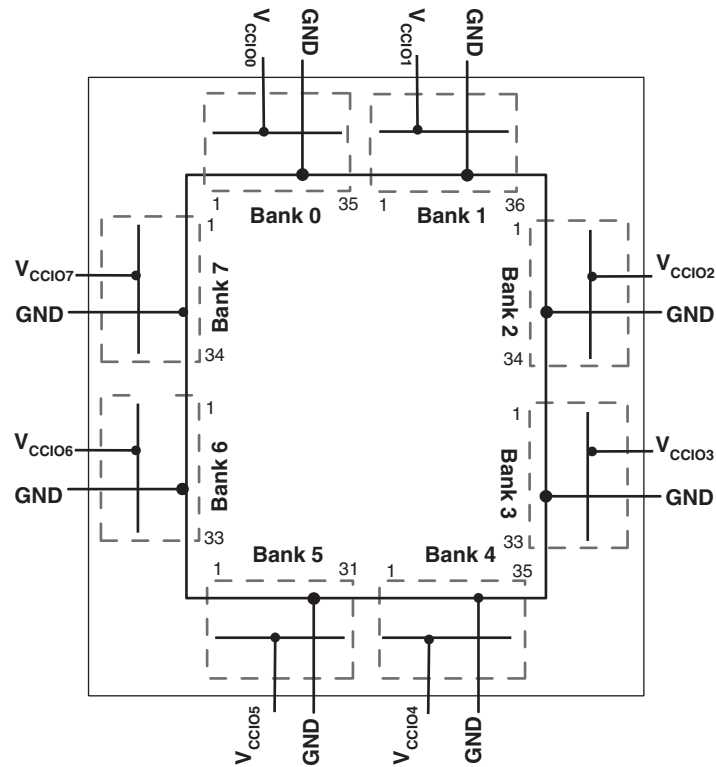


Figure 2-19. MachXO1200 Banks

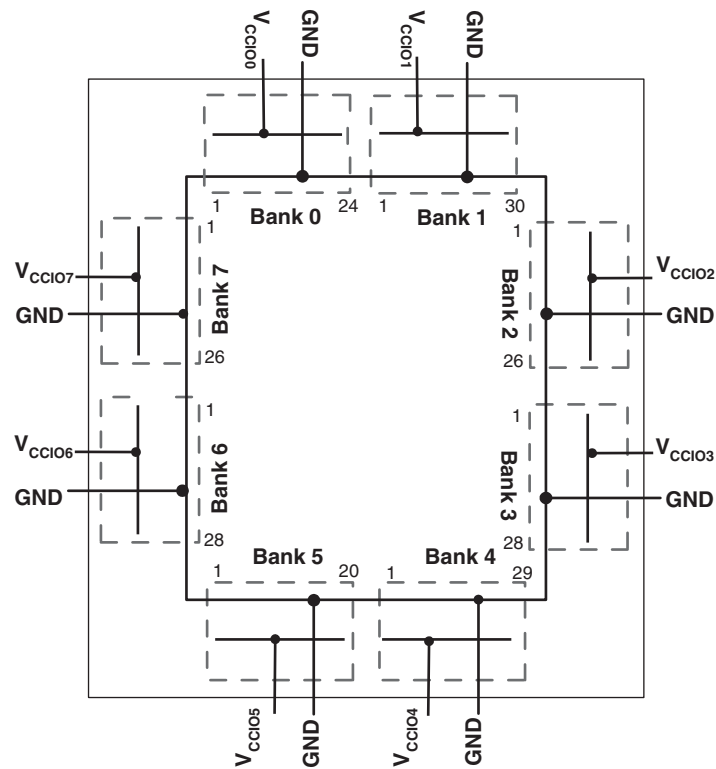
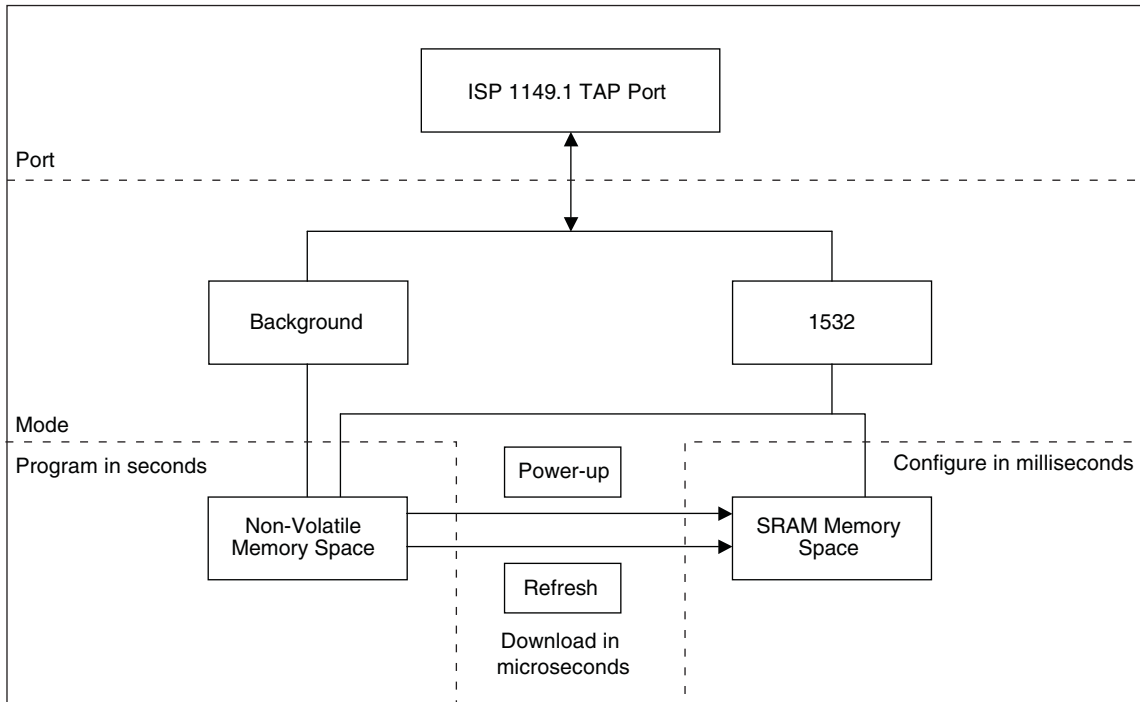


Figure 2-22. MachXO Configuration and Programming



## Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

## MachXO256 and MachXO640 Hot Socketing Specifications<sup>1, 2, 3</sup>

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I <sub>DK</sub>	Input or I/O leakage Current	0 ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX)	—	—	+/-1000	μA

1. Insensitive to sequence of V<sub>CC</sub>, V<sub>CCAUX</sub>, and V<sub>CCIO</sub>. However, assumes monotonic rise/fall rates for V<sub>CC</sub>, V<sub>CCAUX</sub>, and V<sub>CCIO</sub>.
2. 0 ≤ V<sub>CC</sub> ≤ V<sub>CC</sub> (MAX), 0 ≤ V<sub>CCIO</sub> ≤ V<sub>CCIO</sub> (MAX) and 0 ≤ V<sub>CCAUX</sub> ≤ V<sub>CCAUX</sub> (MAX).
3. I<sub>DK</sub> is additive to I<sub>PU</sub>, I<sub>PD</sub> or I<sub>BH</sub>.

## MachXO1200 and MachXO2280 Hot Socketing Specifications<sup>1, 2, 3</sup>

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Non-LVDS General Purpose sysIOs</b>						
I <sub>DK</sub>	Input or I/O Leakage Current	0 ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX.)	—	—	+/-1000	μA
<b>LVDS General Purpose sysIOs</b>						
I <sub>DK_LVDS</sub>	Input or I/O Leakage Current	V <sub>IN</sub> ≤ V <sub>CCIO</sub>	—	—	+/-1000	μA
		V <sub>IN</sub> > V <sub>CCIO</sub>	—	35	—	mA

1. Insensitive to sequence of V<sub>CC</sub>, V<sub>CCAUX</sub>, and V<sub>CCIO</sub>. However, assumes monotonic rise/fall rates for V<sub>CC</sub>, V<sub>CCAUX</sub>, and V<sub>CCIO</sub>.
2. 0 ≤ V<sub>CC</sub> ≤ V<sub>CC</sub> (MAX), 0 ≤ V<sub>CCIO</sub> ≤ V<sub>CCIO</sub> (MAX), and 0 ≤ V<sub>CCAUX</sub> ≤ V<sub>CCAUX</sub> (MAX).
3. I<sub>DK</sub> is additive to I<sub>PU</sub>, I<sub>PW</sub> or I<sub>BH</sub>.

## DC Electrical Characteristics

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I <sub>IL</sub> , I <sub>IH</sub> <sup>1, 4, 5</sup>	Input or I/O Leakage	0 ≤ V <sub>IN</sub> ≤ (V <sub>CCIO</sub> - 0.2V)	—	—	10	μA
		(V <sub>CCIO</sub> - 0.2V) < V <sub>IN</sub> ≤ 3.6V	—	—	40	μA
I <sub>PU</sub>	I/O Active Pull-up Current	0 ≤ V <sub>IN</sub> ≤ 0.7 V <sub>CCIO</sub>	-30	—	-150	μA
I <sub>PD</sub>	I/O Active Pull-down Current	V <sub>IL</sub> (MAX) ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX)	30	—	150	μA
I <sub>BHLS</sub>	Bus Hold Low sustaining current	V <sub>IN</sub> = V <sub>IL</sub> (MAX)	30	—	—	μA
I <sub>BHHS</sub>	Bus Hold High sustaining current	V <sub>IN</sub> = 0.7V <sub>CCIO</sub>	-30	—	—	μA
I <sub>BHLO</sub>	Bus Hold Low Overdrive current	0 ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX)	—	—	150	μA
I <sub>BHHO</sub>	Bus Hold High Overdrive current	0 ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX)	—	—	-150	μA
V <sub>BHT</sub> <sup>3</sup>	Bus Hold trip Points	0 ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> (MAX)	V <sub>IL</sub> (MAX)	—	V <sub>IH</sub> (MIN)	V
C1	I/O Capacitance <sup>2</sup>	V <sub>CCIO</sub> = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V <sub>CC</sub> = Typ., V <sub>IO</sub> = 0 to V <sub>IH</sub> (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance <sup>2</sup>	V <sub>CCIO</sub> = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V <sub>CC</sub> = Typ., V <sub>IO</sub> = 0 to V <sub>IH</sub> (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T<sub>A</sub> 25°C, f = 1.0MHz
3. Please refer to V<sub>IL</sub> and V<sub>IH</sub> in the sysIO Single-Ended DC Electrical Characteristics table of this document.
4. Not applicable to SLEEPN pin.
5. When V<sub>IH</sub> is higher than V<sub>CCIO</sub>, a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For MachXO1200 and MachXO2280 true LVDS output pins, V<sub>IH</sub> must be less than or equal to V<sub>CCIO</sub>.



**Supply Current (Sleep Mode)<sup>1, 2</sup>**

Symbol	Parameter	Device	Typ. <sup>3</sup>	Max.	Units
I <sub>CC</sub>	Core Power Supply	LCMXO256C	12	25	μA
		LCMXO640C	12	25	μA
		LCMXO1200C	12	25	μA
		LCMXO2280C	12	25	μA
I <sub>CCAUX</sub>	Auxiliary Power Supply	LCMXO256C	1	15	μA
		LCMXO640C	1	25	μA
		LCMXO1200C	1	45	μA
		LCMXO2280C	1	85	μA
I <sub>CCIO</sub>	Bank Power Supply <sup>4</sup>	All LCMXO 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the V<sub>CCIO</sub> or GND.
2. Frequency = 0MHz.
3. T<sub>A</sub> = 25°C, power supplies at nominal voltage.
4. Per Bank.

**Supply Current (Standby)<sup>1, 2, 3, 4</sup>**
**Over Recommended Operating Conditions**

Symbol	Parameter	Device	Typ. <sup>5</sup>	Units
I <sub>CC</sub>	Core Power Supply	LCMXO256C	7	mA
		LCMXO640C	9	mA
		LCMXO1200C	14	mA
		LCMXO2280C	20	mA
		LCMXO256E	4	mA
		LCMXO640E	6	mA
		LCMXO1200E	10	mA
		LCMXO2280E	12	mA
I <sub>CCAUX</sub>	Auxiliary Power Supply V <sub>CCAUX</sub> = 3.3V	LCMXO256E/C	5	mA
		LCMXO640E/C	7	mA
		LCMXO1200E/C	12	mA
		LCMXO2280E/C	13	mA
I <sub>CCIO</sub>	Bank Power Supply <sup>6</sup>	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V<sub>CCIO</sub> or GND.
3. Frequency = 0MHz.
4. User pattern = blank.
5. T<sub>J</sub> = 25°C, power supplies at nominal voltage.
6. Per Bank. V<sub>CCIO</sub> = 2.5V. Does not include pull-up/pull-down.

## sysIO Recommended Operating Conditions

Standard	V <sub>CCIO</sub> (V)		
	Min.	Typ.	Max.
LVC MOS 3.3	3.135	3.3	3.465
LVC MOS 2.5	2.375	2.5	2.625
LVC MOS 1.8	1.71	1.8	1.89
LVC MOS 1.5	1.425	1.5	1.575
LVC MOS 1.2	1.14	1.2	1.26
LVTTL	3.135	3.3	3.465
PCI <sup>3</sup>	3.135	3.3	3.465
LVDS <sup>1,2</sup>	2.375	2.5	2.625
LVPECL <sup>1</sup>	3.135	3.3	3.465
BLVDS <sup>1</sup>	2.375	2.5	2.625
RSDS <sup>1</sup>	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers
3. Input on the top bank of the MachXO1200 and MachXO2280 only.

## sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V <sub>IL</sub>		V <sub>IH</sub>		V <sub>OL</sub> Max. (V)	V <sub>OH</sub> Min. (V)	I <sub>OL</sub> <sup>1</sup> (mA)	I <sub>OH</sub> <sup>1</sup> (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVC MOS 3.3	-0.3	0.8	2.0	3.6	0.4	V <sub>CCIO</sub> - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	2.4	16	-16
					0.4	V <sub>CCIO</sub> - 0.4	12, 8, 4	-12, -8, -4
LVC MOS 2.5	-0.3	0.7	1.7	3.6	0.4	V <sub>CCIO</sub> - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
LVC MOS 1.8	-0.3	0.35V <sub>CCIO</sub>	0.65V <sub>CCIO</sub>	3.6	0.4	V <sub>CCIO</sub> - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
LVC MOS 1.5	-0.3	0.35V <sub>CCIO</sub>	0.65V <sub>CCIO</sub>	3.6	0.4	V <sub>CCIO</sub> - 0.4	8, 4	-8, -4
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
LVC MOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	V <sub>CCIO</sub> - 0.4	6, 2	-6, -2
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
LVC MOS 1.2 ("E" Version)	-0.3	0.35V <sub>CC</sub>	0.65V <sub>CC</sub>	3.6	0.4	V <sub>CCIO</sub> - 0.4	6, 2	-6, -2
					0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
PCI	-0.3	0.3V <sub>CCIO</sub>	0.5V <sub>CCIO</sub>	3.6	0.1V <sub>CCIO</sub>	0.9V <sub>CCIO</sub>	1.5	-0.5

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed n \* 8mA. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.

## Pin Information Summary

Pin Type		LCMXO256C/E		LCMXO640C/E				
		100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O		78	78	74	113	74	101	159
Differential Pair User I/O <sup>1</sup>		38	38	17	43	17	42	79
Muxed		6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5
VCC		2	2	2	4	2	4	4
VCCAUX		1	1	1	2	1	2	2
VCCIO	Bank0	3	3	2	2	2	2	4
	Bank1	3	3	2	2	2	2	4
	Bank2	—	—	2	2	2	2	4
	Bank3	—	—	2	2	2	2	4
GND		8	8	10	12	10	12	18
NC		0	0	0	0	0	0	52
Single Ended/Differential I/O per Bank	Bank0	41/20	41/20	18/5	29/10	18/5	26/11	42/21
	Bank1	37/18	37/18	21/4	30/11	21/4	27/12	40/20
	Bank2	—	—	14/2	24/9	14/2	21/9	36/18
	Bank3	—	—	21/6	30/13	21/6	27/10	40/20

1. These devices support emulated LVDS outputs. LVDS inputs are not supported.

Pin Type		LCMXO1200C/E				LCMXO2280C/E				
		100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O		73	113	101	211	73	113	101	211	271
Differential Pair User I/O <sup>1</sup>		27	48	42	105	30	47	41	105	134
Muxed		6	6	6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5	5	5
VCC		4	4	4	4	2	4	4	4	6
VCCAUX		2	2	2	2	2	2	2	2	2
VCCIO	Bank0	1	1	1	2	1	1	1	2	2
	Bank1	1	1	1	2	1	1	1	2	2
	Bank2	1	1	1	2	1	1	1	2	2
	Bank3	1	1	1	2	1	1	1	2	2
	Bank4	1	1	1	2	1	1	1	2	2
	Bank5	1	1	1	2	1	1	1	2	2
	Bank6	1	1	1	2	1	1	1	2	2
	Bank7	1	1	1	2	1	1	1	2	2
GND		8	12	12	18	8	12	12	18	24
NC		0	0	0	0	0	0	0	0	0
Single Ended/Differential I/O per Bank	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12	34/17
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15	36/18
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13	34/17
	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14	34/17
	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14	35/17
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10	30/15
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14	34/17
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13	34/17

1. These devices support on-chip LVDS buffers for left and right I/O Banks.

**LCMX0256 and LCMX0640 Logic Signal Connections: 100 TQFP**

Pin Number	LCMX0256				LCMX0640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

**LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP (Cont.)**

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
82	PT9A	1			PT12C	1		T
83	GND	-			GND	-		
84	PT8B	1		C	PT11B	1		C
85	PT8A	1		T	PT11A	1		T
86	PT7D	1	PCLK1_1****		PT10B	1	PCLK1_1****	
87	PT6F	0	PCLK0_0****		PT9B	1	PCLK1_0****	
88	PT6D	0		C	PT8F	0		C
89	PT6C	0		T	PT8E	0		T
90	VCCAUX	-			VCCAUX	-		
91	VCC	-			VCC	-		
92	PT5B	0			PT6D	0		
93	PT4B	0			PT6F	0		
94	VCCIO0	0			VCCIO0	0		
95	PT3D	0		C	PT4B	0		C
96	PT3C	0		T	PT4A	0		T
97	PT3B	0			PT3B	0		
98	PT2B	0		C	PT2B	0		C
99	PT2A	0		T	PT2A	0		T
100**	GNDIO0 GNDIO7	-			GNDIO0 GNDIO7	-		

\*Supports true LVDS outputs.

\*\*Double bonded to the pin.

\*\*\*NC for "E" devices.

\*\*\*\*Primary clock inputs are single-ended.

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:  
 144 TQFP (Cont.)**

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
51	TDI	2	TDI		TDI	5	TDI		TDI	5	TDI	
52	VCC	-			VCC	-			VCC	-		
53	VCCAUX	-			VCCAUX	-			VCCAUX	-		
54	PB5A	2		T	PB6F	5			PB8F	5		
55	PB5B	2	PCLKT2_1***	C	PB7B	4	PCLK4_1***		PB10F	4	PCLK4_1***	
56	PB5D	2			PB7C	4		T	PB10C	4		T
57	PB6A	2		T	PB7D	4		C	PB10D	4		C
58	PB6B	2	PCLKT2_0***	C	PB7F	4	PCLK4_0***		PB10B	4	PCLK4_0***	
59	GND	-			GND	-			GND	-		
60	PB7C	2			PB9A	4		T	PB12A	4		T
61	PB7E	2			PB9B	4		C	PB12B	4		C
62	PB8A	2			PB9E	4			PB12E	4		
63	VCCIO2	2			VCCIO4	4			VCCIO4	4		
64	GNDIO2	2			GNDIO4	4			GNDIO4	4		
65	PB8C	2		T	PB10A	4		T	PB13A	4		T
66	PB8D	2		C	PB10B	4		C	PB13B	4		C
67	PB9A	2		T	PB10C	4		T	PB13C	4		T
68	PB9C	2		T	PB10D	4		C	PB13D	4		C
69	PB9B	2		C	PB10F	4			PB14D	4		
70**	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
71	PB9D	2		C	PB11C	4		T	PB16C	4		T
72	PB9F	2			PB11D	4		C	PB16D	4		C
73	PR11D	1		C	PR16B	3		C	PR20B	3		C
74	PR11B	1		C	PR16A	3		T	PR20A	3		T
75	PR11C	1		T	PR15B	3		C*	PR19B	3		C
76	PR10D	1		C	PR15A	3		T*	PR19A	3		T
77	PR11A	1		T	PR14D	3		C	PR17D	3		C
78	PR10B	1		C	PR14C	3		T	PR17C	3		T
79	PR10C	1		T	PR14B	3		C*	PR17B	3		C*
80	PR10A	1		T	PR14A	3		T*	PR17A	3		T*
81	PR9D	1			PR13D	3			PR16D	3		
82	VCCIO1	1			VCCIO3	3			VCCIO3	3		
83	GNDIO1	1			GNDIO3	3			GNDIO3	3		
84	PR9A	1			PR12B	3		C*	PR15B	3		C*
85	PR8C	1			PR12A	3		T*	PR15A	3		T*
86	PR8A	1			PR11B	3		C*	PR14B	3		C*
87	PR7D	1			PR11A	3		T*	PR14A	3		T*
88	GND	-			GND	-			GND	-		
89	PR7B	1		C	PR10B	3		C*	PR13B	3		C*
90	PR7A	1		T	PR10A	3		T*	PR13A	3		T*
91	PR6D	1		C	PR8B	2		C*	PR10B	2		C*
92	PR6C	1		T	PR8A	2		T*	PR10A	2		T*
93	VCC	-			VCC	-			VCC	-		
94	PR5D	1			PR6B	2		C*	PR8B	2		C*
95	PR5B	1			PR6A	2		T*	PR8A	2		T*
96	PR4D	1			PR5B	2		C*	PR7B	2		C*
97	PR4B	1		C	PR5A	2		T*	PR7A	2		T*
98	VCCIO1	1			VCCIO2	2			VCCIO2	2		
99	GNDIO1	1			GNDIO2	2			GNDIO2	2		
100	PR4A	1		T	PR4C	2			PR5C	2		

## LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

\*Supports true LVDS outputs.

\*\*NC for "E" devices.

\*\*\*Primary clock inputs are single-ended.

## LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J4	PL8A	3		T	J4	PL13A	6		T*	J4	PL16A	6		T*
J5	PL8B	3		C	J5	PL13B	6		C*	J5	PL16B	6		C*
R1	PL11A	3		T	R1	PL13C	6		T	R1	PL16C	6		T
R2	PL11B	3		C	R2	PL13D	6		C	R2	PL16D	6		C
-	-	-			-	-	-			GND	GND	-		
K5	NC				K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	T*
K4	NC				K4	PL14B	6	LLM0_PLCC_FB_A	C*	K4	PL17B	6	LLM0_PLCC_FB_A	C*
L5	PL10C	3		T	L5	PL14C	6		T	L5	PL17C	6		T
L4	PL10D	3		C	L4	PL14D	6		C	L4	PL17D	6		C
M5	NC				M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	T*
M4	NC				M4	PL15B	6	LLM0_PLCC_IN_A	C*	M4	PL18B	6	LLM0_PLCC_IN_A	C*
N4	PL11C	3		T	N4	PL16A	6		T	N4	PL19A	6		T
N3	PL11D	3		C	N3	PL16B	6		C	N3	PL19B	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
P4	TMS	2	TMS		P4	TMS	5	TMS		P4	TMS	5	TMS	
P2	NC				P2	PB2A	5		T	P2	PB2A	5		T
P3	NC				P3	PB2B	5		C	P3	PB2B	5		C
N5	NC				N5	PB2C	5		T	N5	PB2C	5		T
R3	TCK	2	TCK		R3	TCK	5	TCK		R3	TCK	5	TCK	
N6	NC				N6	PB2D	5		C	N6	PB2D	5		C
T2	PB2A	2		T	T2	PB3A	5		T	T2	PB3A	5		T
T3	PB2B	2		C	T3	PB3B	5		C	T3	PB3B	5		C
R4	PB2C	2		T	R4	PB3C	5		T	R4	PB3C	5		T
R5	PB2D	2		C	R5	PB3D	5		C	R5	PB3D	5		C
P5	PB3A	2		T	P5	PB4A	5		T	P5	PB4A	5		T
P6	PB3B	2		C	P6	PB4B	5		C	P6	PB4B	5		C
T5	PB3C	2		T	T5	PB4C	5		T	T5	PB4C	5		T
M6	TDO	2	TDO		M6	TDO	5	TDO		M6	TDO	5	TDO	
T4	PB3D	2		C	T4	PB4D	5		C	T4	PB4D	5		C
R6	PB4A	2		T	R6	PB5A	5		T	R6	PB5A	5		T
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
T6	PB4B	2		C	T6	PB5B	5		C	T6	PB5B	5		C
N7	TDI	2	TDI		N7	TDI	5	TDI		N7	TDI	5	TDI	
T8	PB4C	2		T	T8	PB5C	5		T	T8	PB6A	5		T
T7	PB4D	2		C	T7	PB5D	5		C	T7	PB6B	5		C
M7	NC				M7	PB6A	5		T	M7	PB7C	5		T
M8	NC				M8	PB6B	5		C	M8	PB7D	5		C
T9	VCCAUX	-			T9	VCCAUX	-			T9	VCCAUX	-		
R7	PB4E	2		T	R7	PB6C	5		T	R7	PB8C	5		T
R8	PB4F	2		C	R8	PB6D	5		C	R8	PB8D	5		C
-	-				VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
-	-				GND	GNDIO5	5			GND	GNDIO5	5		
P7	PB5C	2		T	P7	PB6E	5		T	P7	PB9A	4		T
P8	PB5D	2		C	P8	PB6F	5		C	P8	PB9B	4		C
N8	PB5A	2		T	N8	PB7A	4		T	N8	PB10E	4		T
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***	C
P10	PB7B	2		C	P10	PB7D	4		C	P10	PB10D	4		C
P9	PB7A	2		T	P9	PB7C	4		T	P9	PB10C	4		T
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***	C



**LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G2	PL11A	6		T*
H2	PL11B	6		C*
L3	PL11C	6		T
L5	PL11D	6		C
H1	PL12A	6		T*
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
J2	PL12B	6		C*
L4	PL12C	6		T
L6	PL12D	6		C
K2	PL13A	6		T*
K1	PL13B	6		C*
J1	PL13C	6		T
VCC	VCC	-		
L2	PL13D	6		C
M5	PL14D	6		C
M3	PL14C	6	TSALL	T
L1	PL14B	6		C*
M2	PL14A	6		T*
M1	PL15A	6		T*
N1	PL15B	6		C*
M6	PL15C	6		T
M4	PL15D	6		C
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
P1	PL16A	6		T*
P2	PL16B	6		C*
N3	PL16C	6		T
N4	PL16D	6		C
GND	GND	-		
T1	PL17A	6	LLM0_PLLT_FB_A	T*
R1	PL17B	6	LLM0_PLLC_FB_A	C*
P3	PL17C	6		T
N5	PL17D	6		C
R3	PL18A	6	LLM0_PLLT_IN_A	T*
R2	PL18B	6	LLM0_PLLC_IN_A	C*
P4	PL19A	6		T
N6	PL19B	6		C
U1	PL20A	6		T
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		

### LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
T2	PL20B	6		C
P6	TMS	5	TMS	
V1	PB2A	5		T
U2	PB2B	5		C
T3	PB2C	5		T
N7	TCK	5	TCK	
R4	PB2D	5		C
R5	PB3A	5		T
T4	PB3B	5		C
VCC	VCC	-		
R6	PB3C	5		T
P7	PB3D	5		C
U3	PB4A	5		T
T5	PB4B	5		C
V2	PB4C	5		T
N8	TDO	5	TDO	
V3	PB4D	5		C
T6	PB5A	5		T
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		
U4	PB5B	5		C
P8	PB5C	5		T
T7	PB5D	5		C
V4	TDI	5	TDI	
R8	PB6A	5		T
N9	PB6B	5		C
U5	PB6C	5		T
V5	PB6D	5		C
U6	PB7A	5		T
VCC	VCC	-		
V6	PB7B	5		C
P9	PB7C	5		T
T8	PB7D	5		C
U7	PB8A	5		T
V7	PB8B	5		C
M10	VCCAUX	-		
U8	PB8C	5		T
V8	PB8D	5		C
VCCIO5	VCCIO5	5		
GND	GNDIO5	5		
T9	PB8E	5		T
U9	PB8F	5		C
V9	PB9A	4		T

**LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3TN100C	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280C-4TN100C	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280C-5TN100C	2280	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280C-3TN144C	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280C-4TN144C	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280C-5TN144C	2280	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280C-3MN132C	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280C-4MN132C	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280C-5MN132C	2280	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280C-3BN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280C-4BN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280C-5BN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280C-3FTN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280C-4FTN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280C-5FTN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280C-3FTN324C	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280C-4FTN324C	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280C-5FTN324C	2280	1.8V/2.5V/3.3V	271	-5	Lead-Free ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3TN100C	256	1.2V	78	-3	Lead-Free TQFP	100	COM
LCMXO256E-4TN100C	256	1.2V	78	-4	Lead-Free TQFP	100	COM
LCMXO256E-5TN100C	256	1.2V	78	-5	Lead-Free TQFP	100	COM
LCMXO256E-3MN100C	256	1.2V	78	-3	Lead-Free csBGA	100	COM
LCMXO256E-4MN100C	256	1.2V	78	-4	Lead-Free csBGA	100	COM
LCMXO256E-5MN100C	256	1.2V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3TN100C	640	1.2V	74	-3	Lead-Free TQFP	100	COM
LCMXO640E-4TN100C	640	1.2V	74	-4	Lead-Free TQFP	100	COM
LCMXO640E-5TN100C	640	1.2V	74	-5	Lead-Free TQFP	100	COM
LCMXO640E-3MN100C	640	1.2V	74	-3	Lead-Free csBGA	100	COM
LCMXO640E-4MN100C	640	1.2V	74	-4	Lead-Free csBGA	100	COM
LCMXO640E-5MN100C	640	1.2V	74	-5	Lead-Free csBGA	100	COM
LCMXO640E-3TN144C	640	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO640E-4TN144C	640	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO640E-5TN144C	640	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO640E-3MN132C	640	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO640E-4MN132C	640	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO640E-5MN132C	640	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO640E-3BN256C	640	1.2V	159	-3	Lead-Free caBGA	256	COM
LCMXO640E-4BN256C	640	1.2V	159	-4	Lead-Free caBGA	256	COM
LCMXO640E-5BN256C	640	1.2V	159	-5	Lead-Free caBGA	256	COM
LCMXO640E-3FTN256C	640	1.2V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640E-4FTN256C	640	1.2V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640E-5FTN256C	640	1.2V	159	-5	Lead-Free ftBGA	256	COM

Date	Version	Section	Change Summary
November 2006	02.3	DC and Switching Characteristics	Corrections to MachXO “C” Sleep Mode Timing table - value for $t_{WSLEEPN}$ (400ns) changed from max. to min. Value for $t_{WAWAKE}$ (100ns) changed from min. to max. Added Flash Download Time table.
		Architecture	EBR Asynchronous Reset section added.
December 2006	02.4	Pinout Information	Power Supply and NC table; Pin/Ball orientation footnotes added.
February 2007	02.5	Architecture	Updated EBR Asynchronous Reset section.
August 2007	02.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table.
November 2007	02.7	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
June 2009	02.8	Introduction	Added 0.8-mm 256-pin caBGA package to MachXO Family Selection Guide table.
		Pinout Information	Added Logic Signal Connections table for 0.8-mm 256-pin caBGA package.
		Ordering Information	Updated Part Number Description diagram and Ordering Part Number tables with 0.8-mm 256-pin caBGA package information.
July 2010	02.9	DC and Switching Characteristics	Updated sysCLOCK PLL Timing table.
June 2013	03.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
		DC and Switching Characteristics	MachXO1200 and MachXO2280 Hot Socketing Specifications table – Removed footnote 4. Added MachXO Programming/Erase Specifications table.